



Product Change Notification: DSN0-03YRGH168

Date:

07-Sep-2026

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors, Memory

Notification Subject:

CCB 8447 Initial Notice: Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

Affected CPNs:

[DSNO-03YRGH168_Affected_CPN_09072026.pdf](#)

[DSNO-03YRGH168_Affected_CPN_09072026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change(Yes/No)
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Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	CuPdAu	CuPdAu	No
Die Attach Material	8006NS	8006NS	No
Molding Compound Material	G600V	G600V G630AY	Yes
Lead-Frame Material	CDA194	CDA194	No
DAP Surface Prep	Ag-RT	Ag	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying G630AY as additional molding compound material at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					October 2026			
Work Week	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date		x							
Qual Report Availability						x			
Final PCN Issue Date						x			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 07, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-03YRGH168_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

93LC46AT-E/OT
93LC46BT-I/OT
93AA46BT-I/OT
93LC46BT-E/OT
93C46BT-I/OT
93C46BT-E/OT
93C46AT-I/OT
93C46AT-E/OT
93LC56AT-I/OT
93AA56AT-I/OT
93LC56AT-E/OT
93C56AT-I/OT
93C86BT-I/OT
93C86BT-E/OT
25LC020AT-I/OT
25AA020AT-I/OT
25AA02E48T-I/OT
25AA02E64T-I/OT
25AA02UIDT-I/OT
25LC020AT-E/OT
25LC040AT-I/OT
25AA040AT-I/OT
25LC040AT-E/OT
PIC10F220-E/OT043
PIC10F220-E/OT
PIC10F220-I/OT
PIC10F220T-I/OT027
PIC10F220T-I/OT035
PIC10F220T-I/OT040
PIC10F220T-I/OT
PIC10F220T-E/OT030
PIC10F220T-E/OT

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PIC10F222-E/OT

MTCH101-I/OT

PIC10F222-I/OT

PIC10F222T-I/OT020

PIC10F222T-I/OT032

PIC10F222T-I/OT033

PIC10F222T-I/OT039

PIC10F222T-I/OT044

MTCH101T-I/OT

PIC10F222T-I/OT055

PIC10F222T-I/OT056

PIC10F222T-I/OT058

PIC10F222T-I/OT059

PIC10F222T-I/OT062

PIC10F222T-I/OT

PIC10F222T-E/OT

PIC10F222T-I/OT057

24VL025T/OT

34AA02T-I/OT

34LC02T-E/OT

34AA02T-E/OT

24AA025E48T-I/OT

24AA025E64T-I/OT

24AA025UIDT-I/OT

24AA025E48T-E/OT

24AA025E64T-E/OT

93LC56BT-I/OT

93AA56BT-I/OT

93LC56BT-E/OT

93LC66BT-I/OT

93AA66BT-I/OT

93LC66BT-E/OT

93LC66AT-I/OT

93AA66AT-I/OT

93LC66AT-E/OT

93C66BT-I/OT

93C66BT-E/OT

93LC86AT-I/OT

93AA86AT-I/OT

93LC86AT-E/OT

93LC46AT-I/OT

93AA46AT-I/OT

93AA46AE48T-I/OT

93C56AT-E/OT

93C56BT-I/OT

93C56BT-E/OT

93C66AT-I/OT

93C66AT-E/OT

93LC76BT-I/OT

93AA76BT-I/OT

24LC025T-I/OT

24AA025T-I/OT

24LC025T-E/OT

24VL014T/OT

24LC014T-I/OT

24AA014T-I/OT

24LC014T-E/OT

24C01CT-I/OT

24C01CT-E/OT

34VL02T/OT

34LC02T-I/OT

PIC10F200T-I/OT223

PIC10F200T-I/OT224

PIC10F200T-I/OT225

PIC10F200T-I/OT226

PIC10F200T-I/OT227

PIC10F200T-I/OT228

PIC10F200T-I/OT

PIC10F200T-E/OT030

PIC10F200T-E/OT147

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PIC10F200T-E/OT186

PIC10F200T-E/OT191

PIC10F200T-E/OT198

PIC10F200T-E/OT

PIC10F202-E/OT

PIC10F202-I/OT

PIC10F202T-I/OT065

PIC10F202T-I/OT085

PIC10F202T-I/OT105

PIC10F202T-I/OT108

PIC10F202T-I/OT

PIC10F202T-E/OT081

PIC10F202T-E/OT096

PIC10F202T-E/OT

PIC10F204-E/OT

PIC10F204-I/OT

PIC10F204T-I/OT043

PIC10F204T-I/OT051

PIC10F204T-I/OT054

PIC10F204T-I/OT

PIC10F204T-E/OT028

PIC10F204T-E/OT038

PIC10F204T-E/OT050

PIC10F204T-E/OT

PIC10F206-E/OT

PIC10F206-I/OT

PIC10F206T-I/OT030

PIC10F206T-I/OT031

PIC10F206T-I/OT032

PIC10F206T-I/OT043

PIC10F206T-I/OT

PIC10F206T-E/OT

93LC76BT-E/OT

93LC76AT-I/OT

93AA76AT-I/OT

93LC76AT-E/OT

93LC86BT-I/OT

93AA86BT-I/OT

93LC86BT-E/OT

93C76AT-I/OT

93C76AT-E/OT

93C76BT-I/OT

93C76BT-E/OT

93C86AT-I/OT

93C86AT-E/OT

25LC010AT-I/OT

25AA010AT-I/OT

25LC010AT-E/OT

PIC10F200-E/OT

PIC10F200-I/OT

PIC10F200T-I/OT102

PIC10F200T-I/OT108

PIC10F200T-I/OT151

PIC10F200T-I/OT153

PIC10F200T-I/OT169

PIC10F200T-I/OT177

PIC10F200T-I/OT182

PIC10F200T-I/OT185

PIC10F200T-I/OT192

PIC10F200T-I/OT195

PIC10F200T-I/OT196

PIC10F200T-I/OT202

PIC10F200T-I/OT208

PIC10F200T-I/OT209

PIC10F200T-I/OT212

PIC10F200T-I/OT221

PIC10F200T-I/OT222



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QUALIFICATION PLAN SUMMARY

PCN #: DSNO-03YRGH168

Date:

August 27, 2026

Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

Purpose: Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

CCB No.: 8447

<u>Misc.</u>	Assembly site	MMT
	BD Number	BD-004625-01
	MP Code (MPC)	DECA14C8XAXF
	Part Number (CPN)	PIC10F220-E/OT
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	BAG
	Base Quantity Multiple (BQM)	3000
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	72 x 41
	Material	CDA194
	DAP Surface Prep	Ag
	Treatment	Non-Roughening
	Process	Stamped
	Part Number	10100602
	Lead Plating	Matte tin
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	8006NS
	Conductive	No
<u>MC</u>	Part Number	G630AY
<u>PKG</u>	Package Type	SOT-23
	Pin/Ball Count	6

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5			30 bonds from a min. 5 devices.
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5			
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5			
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25C and hot temp 125C.	45	5	3	150	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C and 125C. MSL1/260	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and hot temp 125C.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles Electrical test pre and post stress at hot temp 125C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.